

Docket No.: P2000,0171



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By: Bruno Acklin et al.

Date: October 9, 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Bruno Acklin et al.
Applic. No. : 09/932,878
Filed : August 20, 2001
Title : Method for Producing Semiconductor Laser Components

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INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

German Patent DE 196 44 941 C1 (Dohle et al.), dated January 15, 1998, high-power diode laser and method for mounting it;

German Published, Non-Prosecuted Patent Application DE 40 17 698 A1 (Seipler), dated December 5, 1991, method for building sensors using thick film technology;

German Published, Non-Prosecuted Patent Application DE 43 19 944 A1 (Schulz-Harder), dated December 8, 1994, multiple substrate as well as method for producing it;

German Published, Non-Prosecuted Patent Application DE 198 21 544 A1 (Lorenzen et al.), dated December 16, 1999, diode laser component and method for producing it;

German Published, Non-Prosecuted Patent Application DE 198 27 414 A1 (Schulz-Harder), dated December 23, 1999, method for producing a metal ceramic substrate;

L. J. Missaggia et al.: "Microchannel Heat Sinks for Two-Dimensional High-Power-Density Diode Laser Arrays", IEEE Journal of Quantum Electronics, Vol. 25, No. 9, September 1989, pp. 1988-1992;

Data sheet for laser diode SPL CGxx, xx=81, 94 or 98, Osram Opto Semiconductors, January 1, 2000.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,


Mark P. Weichselbaum
Reg. No. 43,248

For Applicants

Date: October 9, 2001

Lerner And Greenberg, P.A.
Post Office Box 2480
Hollywood, FL 33022-2480
Tel: (954) 925-1100
Fax: (954) 925-1101

/bmb



FORM PTO-1449 SUBSTITUTE U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		Attorney Docket No.: P2000,0171	Applic. No. 09/932,878
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))		Applicant Bruno Acklin et al.	
		Filing Date August 20, 2001	Group Art Unit 0.0

U.S. PATENT DOCUMENTS

EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A						
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

FOREIGN PATENT DOCUMENT

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
	J	196 44 941 C1	01/15/98	Germany			X
	K	40 17 698 A1	12/05/91	Germany			X
	L	43 19 944 A1	12/08/94	Germany			X
	M	198 21 544 A1	12/16/99	Germany			X
	N	198 27 414 A1	12/23/99	Germany			X

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

O	L. J. Missaggia et al.: "Microchannel Heat Sinks for Two-Dimensional High-Power-Density Diode Laser Arrays", IEEE Journal of Quantum Electronics, Vol. 25, No. 9, September 1989, pp. 1988-1992
P	Data sheet for laser diode SPL CGxx, xx=81, 94 or 98, Osram Opto Semiconductors, January 1, 2000
EXAMINER	DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609;
Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.